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SGLS366A - AUGUST 2006-REVISED DECEMBER 2010

# SINGLE D-TYPE FLIP-FLOP WITH ASYNCHRONOUS CLEAR

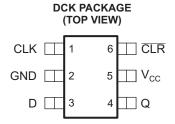
Check for Samples: SN74LVC1G175-EP

#### **FEATURES**

- Supports 5-V V<sub>CC</sub> Operation
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 4.3 ns at 3.3 V
- Low Power Consumption, 10-μA Max I<sub>CC</sub>
- ±24-mA Output Drive at 3.3 V
- I<sub>off</sub> Supports Partial Power-Down-Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly/Test Site
- One Fabrication Site
- Available in Military (–55°C/125°C)
  Temperature Range<sup>(1)</sup>
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability



(1) Additional temperature ranges available - contact factory

### **DESCRIPTION/ORDERING INFORMATION**

This single D-type flip-flop is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

The SN74LVC1G175 has an asynchronous clear ( $\overline{\text{CLR}}$ ) input. When  $\overline{\text{CLR}}$  is high, data from the input pin (D) is transferred to the output pin (Q) on the clock's (CLK) rising edge. When  $\overline{\text{CLR}}$  is low, Q is forced into the low state, regardless of the clock edge or data on D.

This device is fully specified for partial-power-down applications using  $I_{\text{off}}$ . The  $I_{\text{off}}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

#### ORDERING INFORMATION(1)

T <sub>A</sub>	PACKAGE <sup>(2)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(3)</sup>	
–55°C to 125°C	SOT (SC-70) – DCK	Reel of 3000	CLVC1G175MDCKREP	BUD	

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.
- (2) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.
- (3) The actual top-side marking has one additional character that designates the assembly/test site.



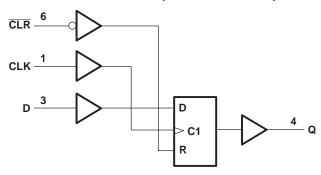
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### **FUNCTION TABLE**

	INPUTS	OUTPUT	
CLR	CLK	D	Q
Н	<b>↑</b>	L	L
Н	<b>↑</b>	Н	Н
Н	H or L	Χ	Qo
L	Χ	X	L

#### LOGIC DIAGRAM (POSITIVE LOGIC)



## Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

•			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	Supply voltage range			
VI	Input voltage range		-0.5	6.5	V
Vo	Voltage range applied to any output in the high-impedance or power-off state (2)			6.5	V
Vo	Voltage range applied to any output in the high or low state (2) (3)		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
$\theta_{JA}$	Package thermal impedance (4)			259	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

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## Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT	
	Committee	Operating	1.65	5.5	V	
V <sub>CC</sub>	Supply voltage	Data retention only	1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>			
. ,	I Pale Java Canada a Nama	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		V	
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V	2		V	
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>			
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>		
. ,		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	.,	
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 3 V to 3.6 V		0.8	V	
		V <sub>CC</sub> = 4.5 V to 5.5 V				
V <sub>I</sub>	Input voltage		0	5.5	V	
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	V	
		V <sub>CC</sub> = 1.65 V		-4		
		V <sub>CC</sub> = 2.3 V		-8		
Он	High-level output current	V 0.V		-16	mA	
		V <sub>CC</sub> = 3 V		-24		
		V <sub>CC</sub> = 4.5 V		-32		
		V <sub>CC</sub> = 1.65 V		4		
		V <sub>CC</sub> = 2.3 V		8		
OL	Low-level output current			16	mA	
		V <sub>CC</sub> = 3 V	24			
		V <sub>CC</sub> = 4.5 V		32		
		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}, 2.5 \text{ V} \pm 0.2 \text{ V}$		20		
Δt/Δv	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
•		$V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$		10		
T <sub>A</sub>	Operating free-air temperature	·	-55	125	°C	

<sup>(1)</sup> All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. See the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITION	NS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT	
	$I_{OH} = -100 \mu A$		1.65 V to 5.5 V	V <sub>CC</sub> - 0.1				
	$I_{OH} = -4 \text{ mA}$		1.65 V	1.2				
V	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			V		
V <sub>ОН</sub>	$I_{OH} = -16 \text{ mA}$	3 V	2.4			V		
	$I_{OH} = -24 \text{ mA}$	3 V	2.3					
	$I_{OH} = -32 \text{ mA}$		4.5 V	3.8				
	I <sub>OL</sub> = 100 μA		1.65 V to 5.5 V			0.1	0.1	
	I <sub>OL</sub> = 4 mA	1.65 V			0.45	0.45		
1/	I <sub>OL</sub> = 8 mA	2.3 V			0.3	V		
$V_{OL}$	I <sub>OL</sub> = 16 mA	3 V	0.4					
	I <sub>OL</sub> = 24 mA	3 V	0.55					
	I <sub>OL</sub> = 32 mA		4.5 V			0.55		
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND		0 to 5.5 V			±1	μΑ	
l <sub>off</sub>	$V_I$ or $V_O = 5.5 \text{ V}$		0			±10	μА	
I <sub>cc</sub>	$V_I = 5.5 \text{ V or GND}, \qquad I_O =$	0	1.65 V to 5.5 V			10	μА	
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other	er inputs at V <sub>CC</sub> or GND	3 V to 5.5 V			500	μΑ	
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND		3.3 V		3		рF	

<sup>(1)</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

## **Timing Requirements**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				V <sub>CC</sub> = ± 0.1		V <sub>CC</sub> = ± 0.2		V <sub>CC</sub> = ± 0.3		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	ock Clock frequency				100		125		150		175	MHz
Dula a diseastan	CLR	Low	6.0		3.5		3.2		3.0		20	
t <sub>w</sub>	Pulse duration	CLK	High or low	4.0		3.5		3.2		3.0		ns
	Catum times hafana CLIKA	Data		3		2.5		2		1.5		
t <sub>su</sub> S	Setup time, before CLK↑	CLR in	active	0.7		0.7		0.7		0.7		ns
t <sub>h</sub>	Hold time, data after CLK	K↑		0.7		0.7		0.7		0.7		ns

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## **Switching Characteristics**

over recommended operating free-air temperature range,  $C_L = 30 \text{ pF or } 50 \text{ pF}$  (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
	(INPOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			100		125		150		175		MHz
	, CLK	0	2.7	16	2.2	9	1.6	8	1.5	5	no
<sup>T</sup> pd	CLR	Q	2.7	16	2.2	9	1.5	8	1.3	5	ns

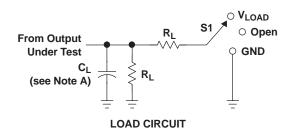
## **Operating Characteristics**

 $T_A = 25$ °C

PARAMETER		TEST	V <sub>CC</sub> = 1.8 V	$V_{CC} = 2.5 V$	$V_{CC} = 3.3 \text{ V}$	$V_{CC} = 5 V$	UNIT
	FARAMETER	CONDITIONS	TYP	TYP	TYP	TYP	UNIT
$C_{pd}$	Power dissipation capacitance	f = 10 MHz	18	19	19	21	pF

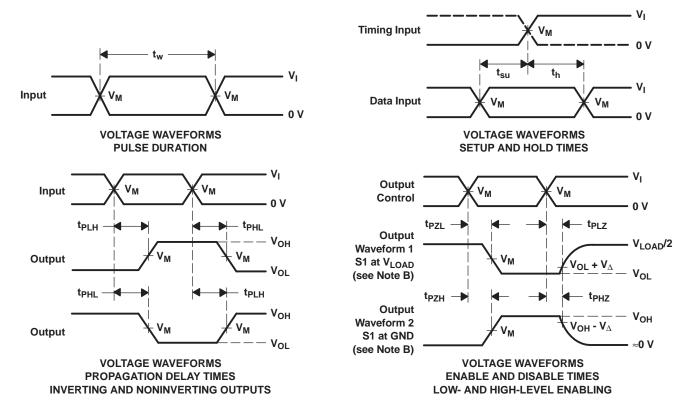


#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub> t <sub>PHZ</sub> /t <sub>PZH</sub>	V <sub>LOAD</sub> GND

V	INPUTS		V	V		В	V	
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	v <sub>r</sub> /t <sub>f</sub> V <sub>M</sub> V <sub>LOAD</sub>		CL	R <sub>L</sub>	$\mathbf{V}_{\Delta}$	
1.8 V ± 0.15 V	V <sub>CC</sub>	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V	
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.15 V	
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	15 pF	<b>1 M</b> Ω	0.3 V	
5 V $\pm$ 0.5 V	V <sub>CC</sub>	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	15 pF	<b>1 M</b> Ω	0.3 V	



NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z<sub>O</sub> = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
- F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

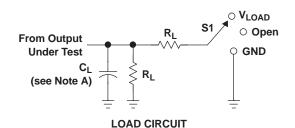
Figure 1. Load Circuit and Voltage Waveforms

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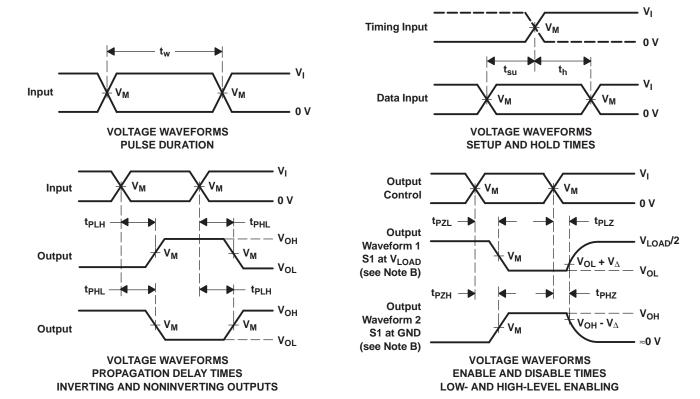


#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
t <sub>PLH</sub> /t <sub>PHL</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

V	INPUTS		.,	· ·		В	V
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\Delta}$
1.8 V $\pm$ 0.15 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
3.3 V $\pm$ 0.3 V	3 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V
5 V $\pm$ 0.5 V	V <sub>CC</sub>	≤2.5 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	50 pF	<b>500</b> Ω	0.3 V



- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ .
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

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## PACKAGE OPTION ADDENDUM

11-Apr-2013

#### PACKAGING INFORMATION

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
CLVC1G175MDCKREP	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	BUD	Samples
CLVC1G175MDCKREPG4	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	BUD	Samples
V62/06633-01XE	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	BUD	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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## **PACKAGE OPTION ADDENDUM**

11-Apr-2013

#### OTHER QUALIFIED VERSIONS OF SN74LVC1G175-EP:

● Catalog: SN74LVC1G175

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

**PACKAGE MATERIALS INFORMATION** 

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## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CLVC1G175MDCKREP	SC70	DCK	6	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3

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#### \*All dimensions are nominal

Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CLVC1G175MDCKREP	SC70	DCK	6	3000	202.0	201.0	28.0	

## DCK (R-PDSO-G6)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



## DCK (R-PDSO-G6)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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